

# PHP/PHB101NQ04T

N-channel TrenchMOS™ standard level FET

Rev. 01 — 12 May 2004

Product data

## 1. Product profile

### 1.1 Description

N-channel enhancement mode field-effect power transistor in a plastic package using TrenchMOS™ technology.

勝特力材料 886-3-5753170  
胜特力电子(上海) 86-21-54151736  
胜特力电子(深圳) 86-755-83298787

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### 1.2 Features

- Standard level threshold
- Very low on-state resistance.

### 1.3 Applications

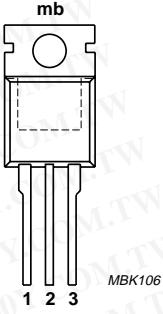
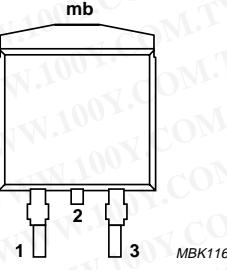
- Motors, lamps, solenoids
- DC-to-DC converters
- Uninterruptible power supplies
- General industrial applications.

### 1.4 Quick reference data

- $V_{DS} \leq 40$  V
- $P_{tot} \leq 157$  W
- $I_D \leq 75$  A
- $R_{DSon} \leq 8$  m $\Omega$ .

## 2. Pinning information

Table 1: Pinning - SOT78 (TO-220AB) and SOT404 (D<sup>2</sup>-PAK), simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)		
2	drain (d)	[1]	
3	source (s)		
mb	mounting base; connected to drain (d)	 MBK106	 MBK116
		<b>SOT78 (TO-220AB)</b>	<b>SOT404 (D<sup>2</sup>-PAK)</b>

[1] It is not possible to make connection to pin 2 of the SOT404 package.



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### 3. Ordering information

**Table 2:** Ordering information

Type number	Package			Version
	Name	Description		
PHP101NQ04T	TO-220AB	Plastic single-ended package; heatsink mounted; 1 mounting hole; 3 leads	SOT78	
PHB101NQ04T	D <sup>2</sup> -PAK	Plastic single-ended surface mounted package; 3 leads (one lead cropped)	SOT404	

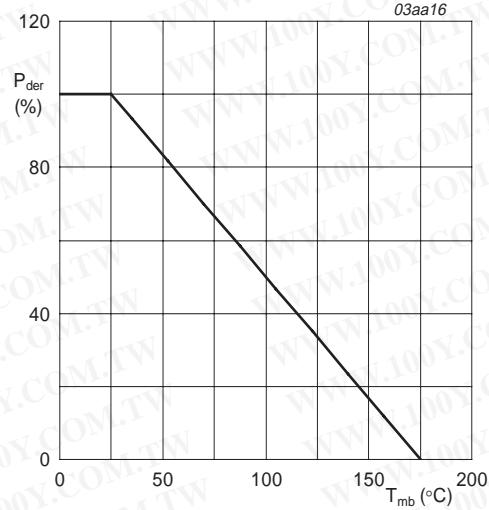
### 4. Limiting values

**Table 3:** Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

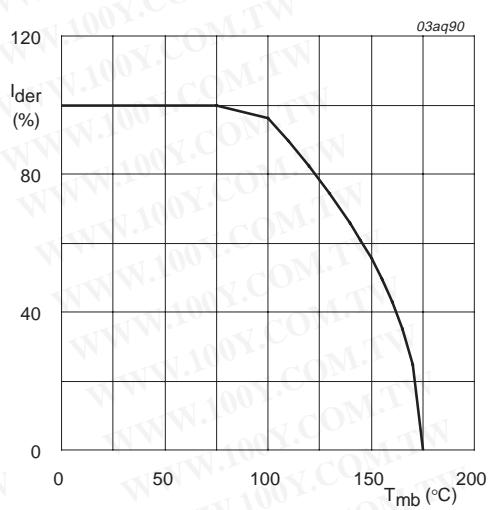
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage (DC)	$25^{\circ}\text{C} \leq T_j \leq 175^{\circ}\text{C}$	-	40	V
$V_{DGR}$	drain-gate voltage (DC)	$25^{\circ}\text{C} \leq T_j \leq 175^{\circ}\text{C}; R_{GS} = 20\text{ k}\Omega$	-	40	V
$V_{GS}$	gate-source voltage (DC)		-	$\pm 20$	V
$I_D$	drain current (DC)	$T_{mb} = 25^{\circ}\text{C}; V_{GS} = 10\text{ V}$ ; Figure 2 and 3	-	75	A
		$T_{mb} = 100^{\circ}\text{C}; V_{GS} = 10\text{ V}$ ; Figure 2	-	71	A
$I_{DM}$	peak drain current	$T_{mb} = 25^{\circ}\text{C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; Figure 3	-	240	A
$P_{tot}$	total power dissipation	$T_{mb} = 25^{\circ}\text{C}$ ; Figure 1	-	157	W
$T_{stg}$	storage temperature		-55	+175	$^{\circ}\text{C}$
$T_j$	junction temperature		-55	+175	$^{\circ}\text{C}$
<b>Source-drain diode</b>					
$I_S$	source (diode forward) current (DC)	$T_{mb} = 25^{\circ}\text{C}$	-	75	A
$I_{SM}$	peak source (diode forward) current	$T_{mb} = 25^{\circ}\text{C}$ ; pulsed; $t_p \leq 10\text{ }\mu\text{s}$	-	240	A
<b>Avalanche ruggedness</b>					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	unclamped inductive load; $I_D = 45\text{ A}$ ; $t_p = 0.17\text{ ms}$ ; $V_{DD} \leq 55\text{ V}$ ; $R_{GS} = 50\text{ }\Omega$ ; $V_{GS} = 10\text{ V}$ ; starting at $T_j = 25^{\circ}\text{C}$	-	200	mJ

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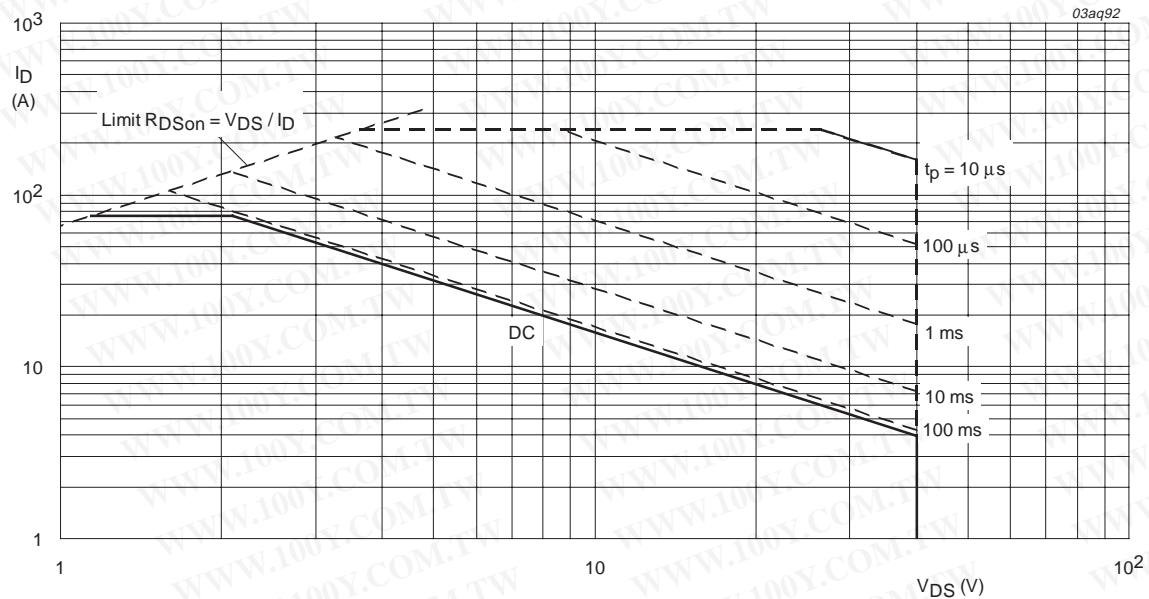
$$P_{der} = \frac{P_{tot}}{P_{tot}(25^\circ\text{C})} \times 100\%$$

Fig 1. Normalized total power dissipation as a function of mounting base temperature.



$$I_{der} = \frac{I_D}{I_{D(25^\circ\text{C})}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature.



T<sub>mb</sub> = 25 °C; I<sub>DM</sub> is single pulse; V<sub>GS</sub> = 10 V.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

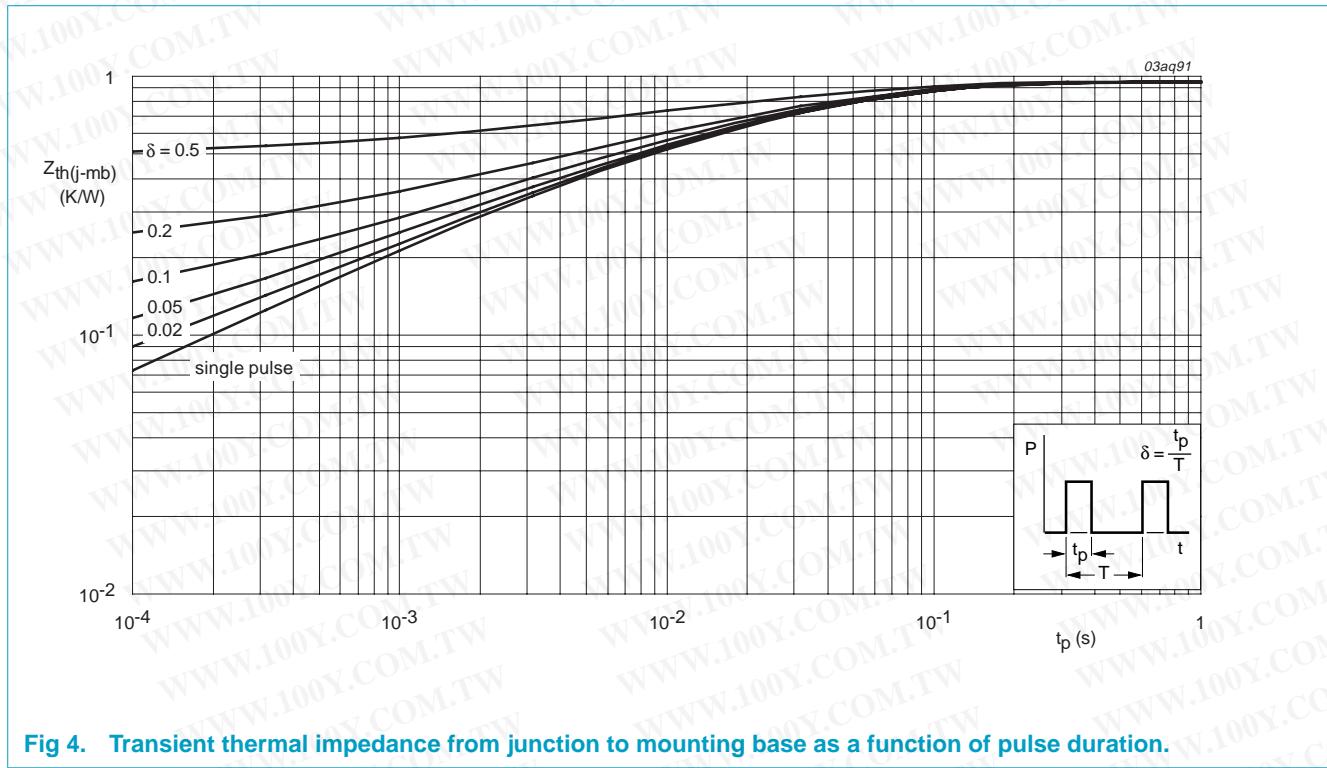
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## 5. Thermal characteristics

**Table 4: Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	Figure 4	-	-	0.95	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient					
	SOT78	vertical in still air	-	60	-	K/W
	SOT404	mounted on a printed-circuit board; vertical in still air; minimum footprint.	-	50	-	K/W

### 5.1 Transient thermal impedance



**Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration.**

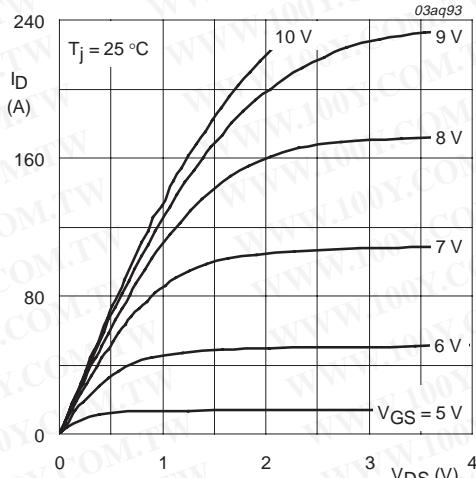
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## 6. Characteristics

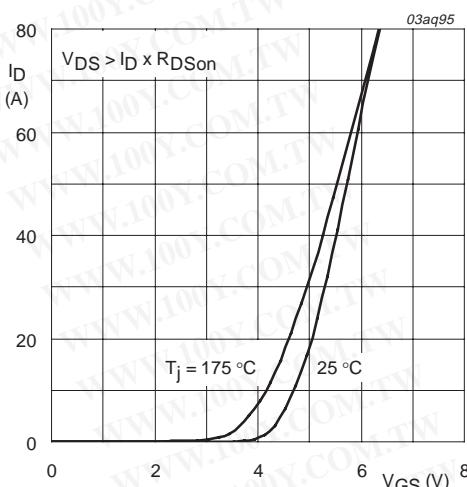
**Table 5: Characteristics** $T_j = 25^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	drain-source breakdown voltage	$I_D = 250 \mu\text{A}; V_{GS} = 0 \text{ V}$				
		$T_j = 25^\circ\text{C}$	40	-	-	V
		$T_j = -55^\circ\text{C}$	36	-	-	V
$V_{GS(\text{th})}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$ ; Figure 9 and 10				
		$T_j = 25^\circ\text{C}$	2	3	4	V
		$T_j = 175^\circ\text{C}$	1	-	-	V
		$T_j = -55^\circ\text{C}$	-	-	4.4	V
$I_{DSS}$	drain-source leakage current	$V_{DS} = 40 \text{ V}; V_{GS} = 0 \text{ V}$				
		$T_j = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$T_j = 175^\circ\text{C}$	-	-	500	$\mu\text{A}$
$I_{GSS}$	gate-source leakage current	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0 \text{ V}$	-	2	100	nA
$R_{DS\text{on}}$	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 25 \text{ A}$ ; Figure 7 and 8				
		$T_j = 25^\circ\text{C}$	-	6.6	8	$\text{m}\Omega$
		$T_j = 175^\circ\text{C}$	-		15.2	$\text{m}\Omega$
<b>Dynamic characteristics</b>						
$Q_{g(\text{tot})}$	total gate charge	$I_D = 25 \text{ A}; V_{DD} = 32 \text{ V}; V_{GS} = 10 \text{ V}$	-	36.6	-	nC
$Q_{gs}$	gate-source charge	Figure 13	-	9.8	-	nC
$Q_{gd}$	gate-drain (Miller) charge		-	12.6	-	nC
$C_{iss}$	input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	2020	-	pF
$C_{oss}$	output capacitance	Figure 11	-	485	-	pF
$C_{rss}$	reverse transfer capacitance		-	215	-	pF
$t_{d(\text{on})}$	turn-on delay time	$V_{DD} = 30 \text{ V}; R_L = 1.2 \Omega$	-	20	-	ns
$t_r$	rise time	$V_{GS} = 10 \text{ V}; R_G = 10 \Omega$	-	51	-	ns
$t_{d(\text{off})}$	turn-off delay time		-	51	-	ns
$t_f$	fall time		-	33	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain (diode forward) voltage	$I_S = 25 \text{ A}; V_{GS} = 0 \text{ V}$ ; Figure 12	-	0.85	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 20 \text{ A}; dI_S/dt = -100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}$	-	53	-	ns
$Q_r$	recovered charge		-	44	-	nC

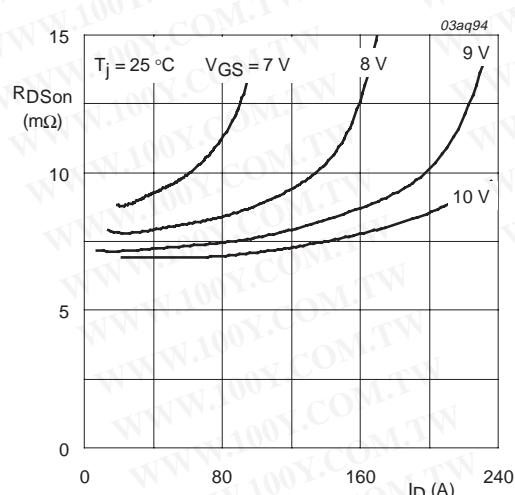
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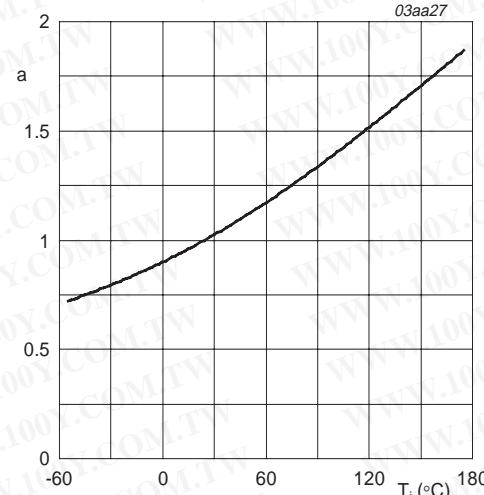
**Fig 5.** Output characteristics: drain current as a function of drain-source voltage; typical values.



**Fig 6.** Transfer characteristics: drain current as a function of gate-source voltage; typical values.

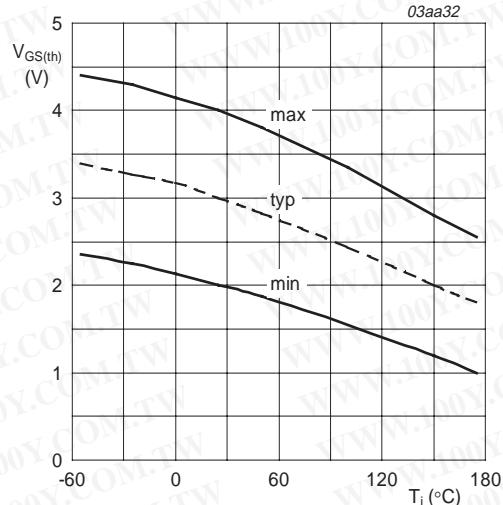


**Fig 7.** Drain-source on-state resistance as a function of drain current; typical values.



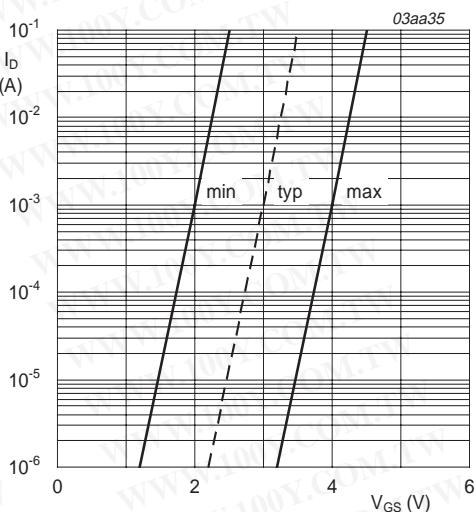
**Fig 8.** Normalized drain-source on-state resistance factor as a function of junction temperature.

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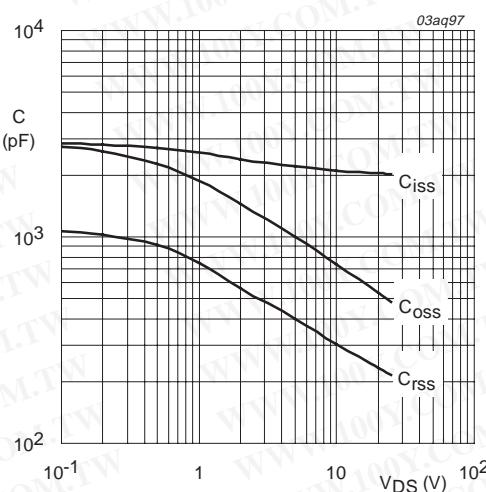
$I_D = 1 \text{ mA}$ ;  $V_{DS} = V_{GS}$

**Fig 9. Gate-source threshold voltage as a function of junction temperature.**



$T_j = 25^\circ\text{C}$ ;  $V_{DS} = 5 \text{ V}$

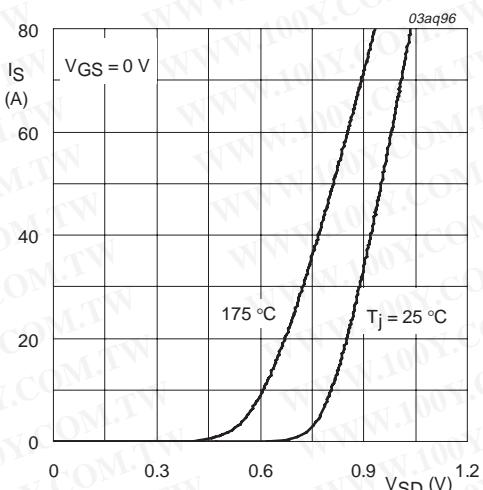
**Fig 10. Sub-threshold drain current as a function of gate-source voltage.**



$V_{GS} = 0 \text{ V}$ ;  $f = 1 \text{ MHz}$

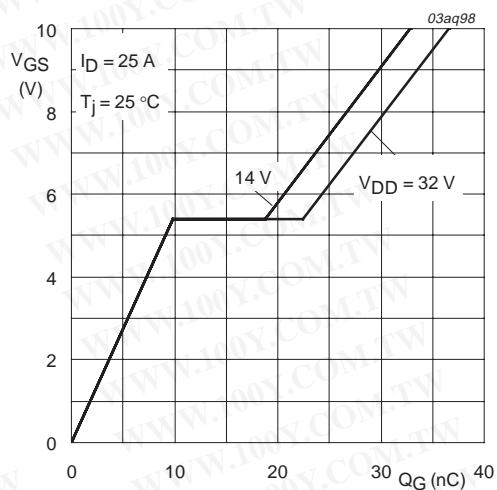
**Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.**

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$T_j = 25^\circ\text{C}$  and  $175^\circ\text{C}$ ;  $V_{GS} = 0\text{ V}$

**Fig 12.** Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 25\text{ A}$ ;  $V_{DD} = 14\text{ V}$  and  $32\text{ V}$

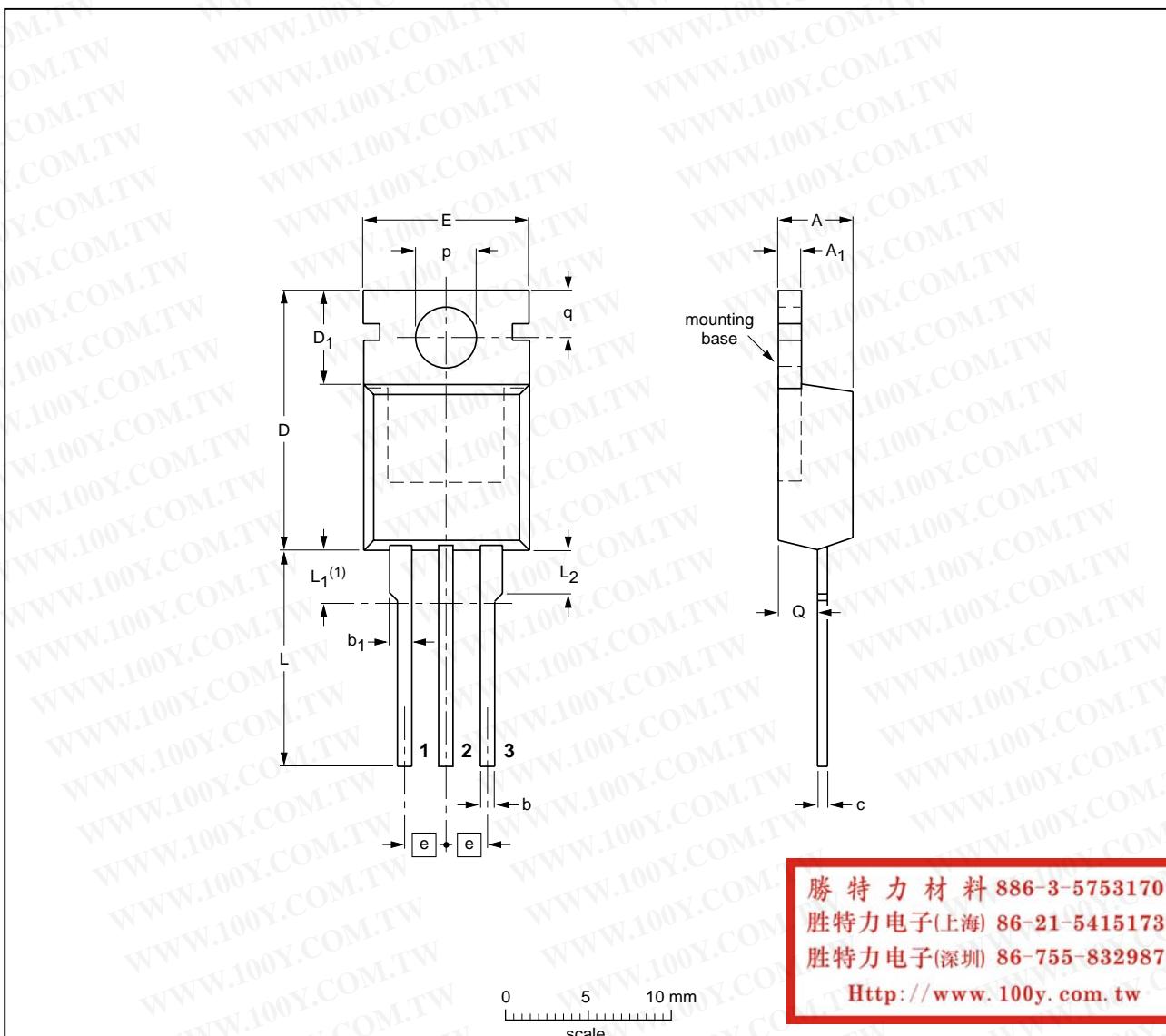
**Fig 13.** Gate-source voltage as a function of gate charge; typical values.

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## 7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



### DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	D <sub>1</sub>	E	e	L	L <sub>1(1)</sub>	L <sub>2</sub> <sub>max.</sub>	p	q	Q
mm	4.5	1.39	0.9	1.3	0.7	15.8	6.4	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.27	0.7	1.0	0.4	15.2	5.9	9.7		13.5	2.79	3.0	3.6	2.7	2.2

### Note

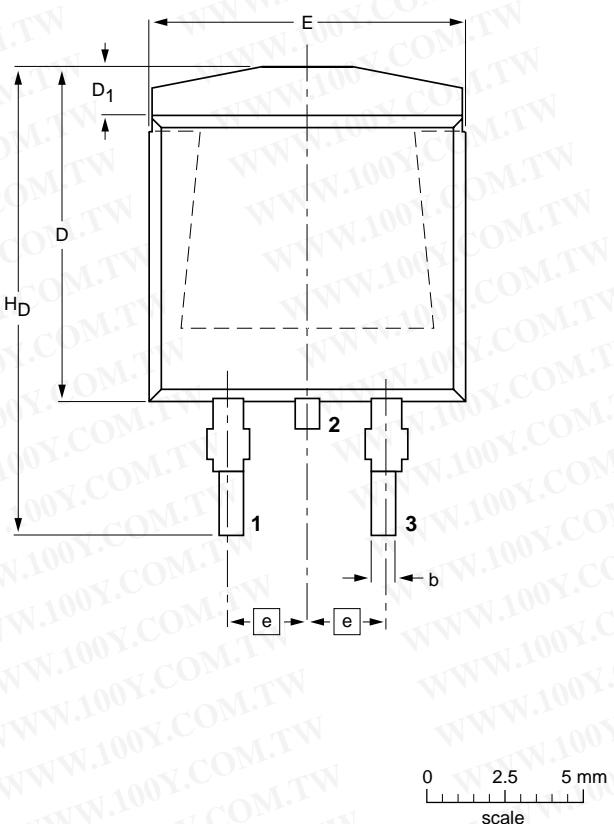
1. Terminals in this zone are not tinned.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT78		3-lead TO-220AB	SC-46			-00-09-07-01-02-16

Fig 14. SOT78 (TO-220AB).

Plastic single-ended surface mounted package (Philips version of D<sup>2</sup>-PAK); 3 leads  
(one lead cropped)

SOT404



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## DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	c	D max.	D <sub>1</sub>	E	e	L <sub>p</sub>	H <sub>D</sub>	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT404						99-06-25 01-02-12

Fig 15. SOT404 (D<sup>2</sup>-PAK)

## 8. Revision history

**Table 6: Revision history**

Rev	Date	CPCN	Description
01	20040512	-	Product data (9397 750 13167).

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## 9. Data sheet status

Level	Data sheet status <sup>[1]</sup>	Product status <sup>[2][3]</sup>	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

## 10. Definitions

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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## 11. Disclaimers

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Date of release: 12 May 2004

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